

TTS EXM Series

200mm Wafer Mounter: EXM-800CS-LUVR-CE-V1

**Wafer MOUNT & BG Tape REMOVER Multi-Function system
With In-line LED UV irradiator TECHNICAL SPECIFICATION**

Revision #1.2A



Model: EXM-800CS-F1-CE Out Side View

1. Features

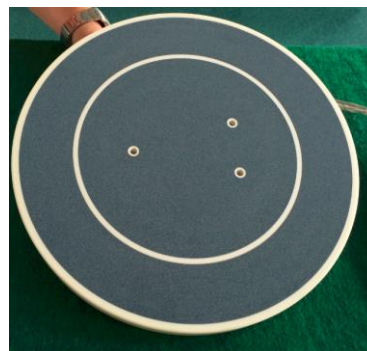
- 1.1 Wafer Size : Up to 8 inch (To be specify wafer type prior to issue the PO)
- 1.2 Load Capacity : One (1) TTS Original Cassette Station
- 1.3 Unload Capacity : One (1) Unload Magazine Station
- 1.4 Cassette : SEMI Standard Open Cassette (Use Even slot only if use Bernoulli finger)
: or DSC
- 1.5 Frame Magazine : SEMI 25 Slots SEMI Standard 6" Frame Cassette
: or SEMI 25 Slots SEMI Standard 8" Frame Cassette
- 1.6 Dicing Frame Type : DISCO Standard DF2-8 or Equivalent Frame Vender
(To be specify wafer type prior to issue the PO)
- 1.7 UPH : 15 - 20 WPH (UPH depends on recipe setting)
- 1.8 Mounting Tape : Normal Roll shape tape (UV & non-UV tapes) or Pre-Cut Type tape(OPT)
- 1.9 Remove Tape : Heat Seal tape Removal Function for BG Tape removal
- 1.10 CCD none contact alignment : CCD sensor and Bernoulli Finger type alignment for thin wafer
- 1.11 Long-life Roller Blade : Newly designed Roller Cutting Blade lasts up to 100,000 times.
(Applicable for normal roll tape)
- 1.12 Heater Capability : Max 60 degree C \pm 3 degree C @ Mount Heat Roller
: Max 60 degree C \pm 3 degree C @ Wafer stage with Soft Si Table
: Room Temp (Roller Cutter)
- 1.13 Big LCD Touch Screen : Big color screen for user friendly and easy operations.
- 1.14 System Recipe capacity : 100 (Max)
- 1.15 Advanced Maintenance Design : Minimum-lubrication, Easy maintenance designs.
1 Year warranty (Main System)
2 Year warranty (Mechanical / Electrical parts)

2. Wafer Mount & BG Tape Remove Function

- 2.1 Removing Module for BG Tape : Heat Seal tape Removal Function for BG Tape removal
: Maximum applicable tape width: 75 mm
- 2.2 Soft Si Rubber Mount Table : Applicable Soft Silicone rubber Universal Table (With Full ESD controlled contacts are)
Soft Silicone rubber table achieves highly secured wafer holding during Dicing Tape Lamination
- 2.3 Remove Table : Applicable Ceramic Universal Table for BG Tape Remove



Soft Si Mount Table



Ceramic Remove Table

- 2.4 Frame Stock Station : Frame Stock station equipped with frame Stock Detection and double frames detection
- 2.5 Applicable Mounting Tape Width : 8" Frame >>>> 295mm (min) – 330mm (max)

3. Optional Function

- 3.1 Thin Wafer Capability : Micro Bernoulli Finger can be handle Thin wafer
- 3.2 Wafer Mapping Capability : Applicable Intelligent Wafer Mapping at Loading Station
- 3.3 In-Line LEDUV Irradiator : Intelligent LED UV irradiation methods
UV Lamp Life Guaranteed@15,000 hours)
- 3.4 SECS/GEM : Applicable TTS Standard SECS/GEM capability following SEMI Stand
- 3.5 Frame Barcode Print & Reader : Applicable Integrated Frame barcode reader by Keyence, Printer by SATO.
- 3.6 Wafer ID OCR : High performance OCR Vision Engine by COGNEX.

(Option must place PO together with equipment)

4. System Dimensions & Utilities

- 4.1 Dimensions : 1900mm (W) x 2500mm (D) x 1900mm (H)
- 4.2 Weight : ≈ 1800kg
- 4.3 Required Power : 200 – 240V, 3KVA Single Phase
- 4.4 Compressed Air : 0.6 MPa (70PSI) Minimum 120 NL / min
- 4.5 Vacuum Source : Minimum 600mmHg 60 NL / min

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